

FlexTRAK™ CD Plasma System

Features and Benefits

- Highly uniform plasma treatment with fast throughput rates
- Production-ready strip handling system
- Easy to use touch screen graphical user interface (GUI)
- Service components accessible via front pull-out shelves
- High volume, small footprint and low cost of ownership



Superior Plasma Processing, Small Footprint, High-Throughput

The FlexTRAK™ CD platform is designed for high throughput processing of lead frame strips, laminated substrates, and other strip-type electronic components, up to 5 strips per plasma cycle.

The patented plasma chamber design provides high uniformity and process repeatability. It ensures all areas of the substrate are treated uniformly, while tight control over process parameters provides highly repeatable results.

The system accommodates a wide range of strip sizes, yielding unmatched production flexibility. Its small chamber volume and proprietary process control system provide short cycle times, with high machine autonomy.

Applications

Plasma for pre-die attach, pre-wire bond, pre-mold encapsulation and pre-underfill such as:

Contamination Removal & Surface Cleaning

- Fluorine & other halogens
- Metals & metal oxides
- Organic compounds

Etching and Surface Roughening

- Improve die adhesion & wire bonding
- Improve mold adhesion & reduce delamination

Surface Activation

- Improve die adhesive flow, eliminate voids and enhance adhesion
- Improve mold material flow, eliminate voids and reduce wire sweep
- Improve underfill flow, eliminate voids, enhance adhesion, and increase wicking speed

Specifications: FlexTRAK™ CD Plasma System

Enclosure Dimensions	W x D x H – Footprint	1068W x 1166D x 1600H; 1966H mm with Light Tower (42W x 46D x 63H; 77H in. with Light Tower)
	Net Weight	430 kg (948 lbs)
	Equipment Clearances	Right, Left, Back – 254 mm (10 in.), Front – 940 mm (37 in.)
Chamber	Maximum Volume	5.5 liters (338 in ³)
Electrodes	Variable Electrode Configurations	Power-Ground, Ground-Power; Power-Power
	Working Area	305W x 305D mm (12W x 12D in.)
RF Power	Standard Wattage	600 W
	Frequency	13.56 MHz
Gas Control	Available Flow Volumes	10, 25, 50, 100, 250 or 500 sccm
	Maximum Number of MFCs	4
Control & Interface	Software Control	EPC with PC-Based Touch Screen Interface
	Remote Interface	SMEMA, SECS/GEM
Vacuum Pump	Standard Dry Pump	16 cfm
	Optional Wet Pump	19.5 cfm
	Optional Purged Dry Pump	16 cfm
	N2 Purged Pump Flow	2 slm
Facilities	Power Supply	220 VAC, 15A, 50/60 Hz, 1-Phase, 12 AWG, 3-Wire
	Process Gas Fitting Size & Type	6.35 mm (0.25 in.) OD Swagelok Tube
	Process Gas Purity	Lab or Electronic Grade
	Process Gas Pressure	0.69 bar (10 psig) min. to 1.03 bar (15 psig) max., regulated
	Purge Gas Fitting Size & Type	6.35 mm (0.25 in.) OD Swagelok Tube
	Purge Gas Purity	Lab or Electronic Grade N2/CDA
	Purge Gas Pressure	2 bar (30 psig) min. to 6.9 bar (100 psig) max., regulated
	Pneumatic Valves Fitting Size & Type	6.35 mm (0.25 in.) OD Swagelok Tube
	Pneumatic Gas Purity	CDA, Oil Free, Dewpoint ≤7°C (45°F), Particulate Size <5 µm
	Pneumatic Gas Pressure	3.45 bar (50 psig) min. to 6.89 bar (100 psig) max., regulated
Compliance	SEMI International	S2/S8 (EH&S/Ergonomics)
	CE Marked	CE Marked
Ancillary Equipment	Gas Generators	Nitrogen, Hydrogen (Requires Additional Non-Optional Hardware)
	Facilities	Chiller, Scrubber

For more information, speak with your local representative or contact your regional office.

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